Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	1 IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information					
Supplier	r Information														
Company name* Company unique ID				ique ID		Unique ID Authority				Response Date*					
onsemi												2024-05-09			
Contact Name			Title - Contact				Phone - Contact*					Email - Contact*			
Product-I	Env-Stewards		Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item Num 1N5942BRLG		Number Mfr Item Name			·	Effective Date Version Manufacturing Site 2024-05-09 CNP		ing Site	We	ight*	UOM	Unit Type		
			BRLG	ZEN SUR30 REG 3W 51V						361.01		mg	Each		
Manufa	cturing Proccess Informa	tion						j				,		·	·
	Terminal Plating / Grid Array Material T		Terminal Base Alloy J-STI		J-STD-020 MSL	_ Rating	Peak Pro	rocess Body Temperature M		re Max Ti	e Max Time at Peak Temperat		Numb	er of Reflow Cyc	eles
	Matte Tin (Sn) - annealed		CU Alloy NA		NA		0 C		30 sec		seconds	3			
Comments															
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated diphenyls of an applicable quantity limit, please indication in the graph of an applicable quantity limit, please indications. Supplier acknowledges that Company will we relied on information provided by others in a minimum and the Supplier agrees that, at a minimum and the Supplier enter into a written agreem source of the Supplier's liability and the Company of the Supplier's liability and the Supplier's liability and the Supplier's liability and the Company of the Supplier's liability and the Supplier's liabi	J 2011/65/EU and implemented by the laws of the Eyl ethers (each a "RoHS restricted substance") in exate below which, if any, RoHS exemption you belie les in this form using appropriate methods to ensure rely on this certification in determining the complian completing this form, and that Supplier may not ha, its suppliers have provided certifications regarding tent with respect to the identified part, the terms and impany's remedies for issues that arise regarding info cable to such part shall apply.	cess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- unce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certifications conditions of that agreement, including any warr	ove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-6_									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.67	mg	Supplier	Silicon (Si)	7440-21-3		2.67	mg
Die Attach Solder	12.67		Supplier	Silver (Ag)	7440-22-4		0.3168	mg
			A	Lead (Pb)	7439-92-1	7a	11.7198	mg
			Supplier	Tin (Sn)	7440-31-5		0.6335	mg
Lead Frame	198.45	mg	В	Nickel (Ni)	7440-02-0		2.183	mg
			Supplier	Copper (Cu)	7440-50-8		196.267	mg
Mold Compound-Black	139.28			Metal Hydroxide	proprietary data		6.964	mg
			Supplier	Carbon Black (C)	1333-86-4		1.3928	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		104.46	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		13.928	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		12.5352	mg
Plating	7.94	mg	Supplier	Tin (Sn)	7440-31-5		7.94	mg